

REMARKS

Claims 13-20, 27-33, 35-40, 55, and 58-66 will pending upon entry of the present amendment. Claim 55 is being amended to include the language of claim 57. Claims 56-57 are being canceled. Claims 1-12, 21-26, 34, and 41-54 were previously canceled. No new matter is being submitted.

Please note that the amendment of claim 55 and the cancellation of claims 56-57 are being submitted to reduce the issues for appeal. The amendment and cancellation do not raise any new issues because all of the claim elements of amended claim 55 were already present in claim 57, which depended on claim 55. Thus, the applicants respectfully request the Examiner to enter the present amendment.

All of the rejections will be addressed in detail in the Appeal Brief to be filed in furtherance of the Notice of Appeal being filed herewith. However, the applicants would like to make a brief comment in response to the Examiner's comments with the Advisory Action dated September 28, 2006. The Examiner pointed to col. 3, lines 36-37 of Ko as teaching the feature of welding an electrically conductive region. That section of Ko does not mention any welding and instead refers to another patent, U.S. Patent No. 5,528,452 to Ko et al. ("Ko II").

Ko II describes in columns 6-7 a process in which a wafer 42 is bonded to a substrate 14 with a conductive feedthrough layer 26, insulating layer 32, and an electrode 24. The paragraph at col. 6, lines 54-65 describes a thermal treatment that deforms the insulating layer 32 around the electrode 26. Rather than teaching welding of the electrode 26, that paragraph teaches that the electrode 26 is not melted, because if both the electrode 26 and the insulating layer 32 were melted, it does not seem that the insulating layer 32 would "deform around the electrode 26" as recited in the '452 patent.

The Director is authorized to charge any additional fees due by way of this Amendment, or credit any overpayment, to our Deposit Account No. 19-1090.

All of the claims remaining in the application are now clearly allowable.
Favorable consideration and a Notice of Allowance are earnestly solicited.

Respectfully submitted,
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